

XPM-2100WG / XPM-2100BWG / XPM-2100AWG

(RoHS Compliant)

10Gb/s 850 nm XFP Multi-Mode Optical Transceiver for 10GbE / 10GFC Applications

FEATURES

- | Support 9.95 Gbps to 10.5 Gbps
- | Complaint with XFP MSA
- | Compliant to IEEE 802.3ae 10GBASE
- | Compliant to 10GFC
- | Link Length up to 300 m with OM3 MMF
- | Link Length up to 82 m with OM2 MMF
- | Link Length up to 33 m with OM1 MMF
- | 850 nm VCSEL Transmitter
- | 2-Wire Interface for Integrated Digital Diagnostic Monitoring
- | No reference clock required
- | Low Power Dissipation < 1.2W
- | **Only Required +3.3 V Power Supply**
- | RoHS Compliant
- | -5 to 70°C Operating : XPM-2100WG
- | -10 to 85°C Operating : XPM-2100BWG
- | -40 to 85°C Operating : XPM-2100AWG
- | Duplex LC Connector

APPLICATIONS

- | 10G Ethernet at 10.3125Gbps
- | 10G Ethernet at 9.953 Gbps
- | 10GFC at 10.51875 Gbps

STANDARD

- | Compliant with XFP MSA
- | Compliant with IEEE 802.3ae-2002
- | Compliant with 10GFC

DESCRIPTION

XPM-2100WG series multi-rate 10G XFP transceiver is designed for serial optical data communications such as 10 Gigabit Ethernet and 10G Fiber Channel. It supports the 10Gbps transmission on both 50/125 μm and 62.5/125 μm MMF.

The transceiver consists of two sections: The transmitter section consists of a directly modulated 850 nm VCSEL, driver and signal conditioner. The receiver section incorporates a PIN photodiode integrated with a trans-impedance preamplifier (TIA) and signal conditioner.

The module is with the XFP 30-pin connector to allow hot plug capability. Integrated Tx and Rx signal conditioners provide high jitter-tolerance for full XFI compliance and no external reference clock required. The internally ac coupled high speed serial I/O simplifies interfacing to external circuitry. Only single 3.3V power supply is needed. The optical output can be disabled by LVTTTL logic high-level input of TX_DIS. Loss of signal (RX_LOS) output is provided to indicate the loss of an input optical signal of receiver.

A serial EEPROM in the transceiver allows the user to access transceiver digital diagnostic monitoring and configuration data via the 2-wire XFP Management Interface. This interface uses a single address, A0h, with a memory map divided into a lower and upper area. Basic digital diagnostic data is held in the lower area while specific data is held in a series of tables in the high memory area.

LASER SAFETY

This transceiver is a Class 1 laser product. It complies with IEC-60825 and FDA 21 CFR 1040.10 and 1040.11. The transceiver must be operated within the specified temperature and voltage limits. The optical ports of the module shall be terminated with an optical connector or with a dust plug.

ORDER INFORMATION

P/No.	Bit Rate (Gb/s)	Distance (m)	Wavelength (nm)	Package	Connector	Temp (°C)	RoHS Compliant
XPM-2100WG	9.95 – 10.52	300/82/33*	850	XFP with DMI	LC	0 to 70	Yes
XPM-2100BWG	9.95 – 10.52	300/82/33*	850	XFP with DMI	LC	-10 to 85	Yes
XPM-2100AWG	9.95 – 10.52	300/82/33*	850	XFP with DMI	LC	-40 to 85	Yes

*: Distance up to 300 m on 50/125 OM3 MMF, up to 82 m for 50/125 mm MMF with model bandwidth 500 MHz-km at 850 nm, & up to 33 m for 62.5/125 mm MMF with model bandwidth 200 MHz-km at 850 nm.

Absolute Maximum Ratings					
Parameter	Symbol	Min	Max	Units	Notes
Storage Temperature	Tstg	-40	85	°C	
Operating Case Temperature	Topr	0	70	°C	XPM-2100WG
		-10	85		XPM-2100BWG
		-40	85		XPM-2100AWG
Relative Humidity	RH	0	85	%	Non condensing
Power Supply Voltage	V _{CC3}	0	3.6	V	
Input Voltage	---	GND	V _{cc3}	V	

Recommended Operating Conditions					
Parameter	Symbol	Min	Typ	Max	Units / Notes
Power Supply Voltage	V _{CC3}	3.13	3.3	3.47	V
Power Supply Current (@3.3V)	I _{CC3}		240	400	mA
Power Dissipation	P _D			1.2	W
Operating Case Temperature	Topr	0		70	°C / XPM-2100WG
		-10		85	°C / XPM-2100BWG
		-40		85	°C / XPM-2100AWG
Data Rate		9.95		10.52	Gb/s

Transmitter Optical Specifications (Topr= 0 to 70°C, Vcc3 = 3.3V ±5%)						
Parameter	Symbol	Min	Typ	Max	Units	Notes
Average Launch Power	P _{O, AVE}	-7.3		-1.0	dBm	1
Launch Power in OMA	P _{O, OMA}	380			μW	1
Extinction Ratio	ER	3			dB	
Output Center Wavelength	λ _c	840	850	860	nm	
Output Spectrum Width	σ _λ		0.25	0.45	nm	RMS (σ)
Relative Intensity Noise	RIN			-128	dB/Hz	
Transmitter and Dispersion Penalty	TDP			3.9	dB	2
Optical Eye Mask	Compliant with IEEE 802.3ae 10GBASE					
Average Launch Power of OFF Transmitter				-30	dBm	

1. Output power is power coupled into a MMF.
2. Measured with a PRBS 2³¹-1 test pattern @10.3125 Gbps for MMF.

Receiver Optical Specifications (Topr= 0 to 70°C, Vcc3 = 3.3V ±5%)						
Parameter	Symbol	Min	Typ	Max	Units	Notes
RX Sensitivity	S _S	---	---	-9.9	dBm	3
Overload in OMA		-1.0	---		dBm	
LOS -- Deasserted	LOS _D	---	---	-9.9	dBm	Transition: low to high
LOS -- Asserted	LOS _A	-25	---	---	dBm	Transition: high to low
LOS -- Hysteresis		1	---		dB	
Wavelength of Operation	λ _c	840		860	nm	
Optical Return Loss	ORL			-12	dB	

3. Average received power @ BER=1E-12 and PRBS 2³¹-1s.

Electrical Characteristics						
Parameter	Symbol	Min	Typ	Max	Units	Notes
High-Speed Signal (CML) Interface Specification						
Input Data Rate		9.95		10.52	Gps	
Differential Input Impedance	R _{in}		100		Ω	
Differential Data Input Amplitude		120		820	mV _{pp}	1, Internally AC coupled
Output Data Rate		9.95		10.52	Gps	
Differential Output Impedance	R _{out}		100		Ω	
Differential Data Output Amplitude		340		850	mV _{pp}	1, Internally AC coupled
Low-Speed Signal (LVTTTL) Interface Specification						
Input High Voltage		2.0		V _{cc}	V	
Input Low Voltage		GND		0.8	V	
Output High Voltage		2.4		V _{cc}	V	
Output Low Voltage		GND		0.5	V	
Reference Clock (LVPECL) Interface Specification						
No reference clock						

1. The differential input and output amplitudes are per XFP MSA mask at points B' and C'.

Transceiver Timing Characteristics						
Parameter	Symbol	Min	Typ	Max	Units	Notes
TX_DIS Assert Time	t _{off}			10	μs	
TX_DIS Negate Time	t _{on}			2	ms	
Time to Initialize	t _{init}			300	ms	
Interrupt Assert Delay	interrupt_on			200	ms	
Interrupt Negate Delay	interrupt_off			500	μs	
P_Down/PST Assert Delay	P_Down/RST_on			100	μs	
P_Down Negate Delay	P_Down/RST_off			300	ms	
Mod_NR Assert Delay	Mod_nr_on			1	ms	
Mod_NR Negate Delay	Mod_nr_off			1	ms	
Mod_Desel Assert Time	T_Mod_Desel			2	ms	
Mod_Desel De-Assert Time	T_Mod_Sel			2	ms	
P_Down Reset Time	T_reset	10			μs	
RX_LOS Assert Delay	T_Los_on			100	μs	
RX_LOS Negate Delay	T_Los_off			100	μs	
Serial ID Clock Rate	f _{SCL}	0		400	kHz	

OPERATING RANGE FOR EACH OPTICAL FIBER TYPE

Fiber Type	Minimum modal bandwidth @850 nm (MHz-km)	Operating range (meters)
62.5 μm MMF	160	2 to 26
	200	2 to 33
50 μm MMF	400	2 to 66
	500	2 to 82
	2000	2 to 300

MANAGEMENT INTERFACE

The structure of the memory map is shown in Figure 1, which is accessible over a 2-wire serial interface at the 8-bit address 1010000X (A0h). The normal 256 byte I2C address space is divided into low and upper blocks of 128 Bytes. The lower block of 128 Bytes is always directly available and is used for the diagnostics and control function. Multiple blocks of memories are available in the upper 128 Bytes of the address space. These are individually addressed through a table select Byte which the user enters into a location in the lower address space. Thus, there is a total available address space of 128*256 = 32 Kbytes in this upper memory space. The contents of Table 01h are listed in Table 1 below. Please refer SFF INF-8077i (Revision 4.5) for detailed information.

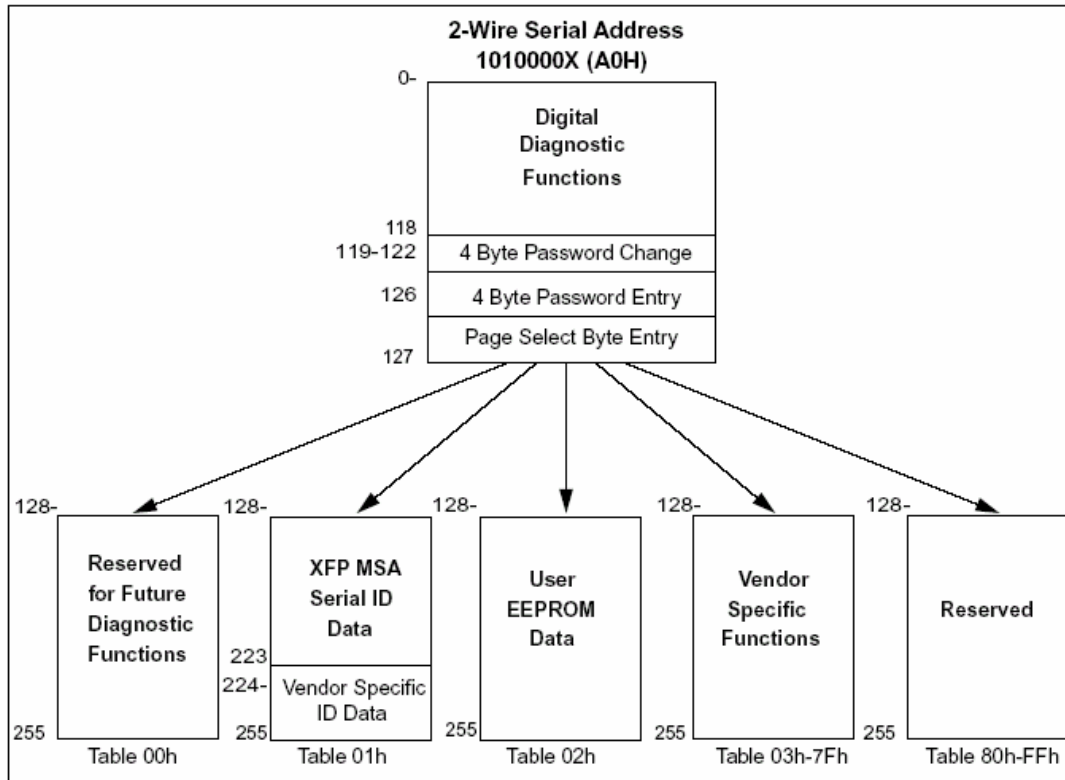


Figure 1. 2-wire Serial Digital Diagnostic Memory Map

Table 1 Monitoring Specification

Data Address	Parameter	Accuracy
96 ~ 97	Temperature	± 3°C
98 ~ 99	Reserved	
100 ~ 101	Tx Bias	± 10%
102 ~ 103	Tx Power	± 2dB
104 ~ 105	Rx Power	± 2dB
106 ~ 107	Vcc3	± 3%

CONNECTION DIAGRAM

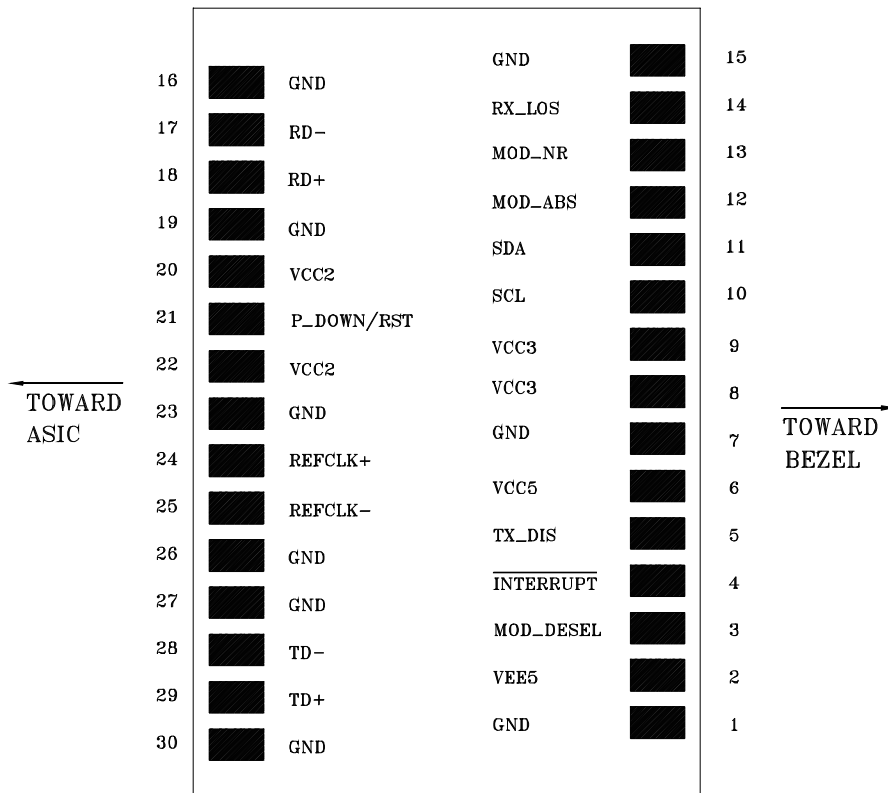


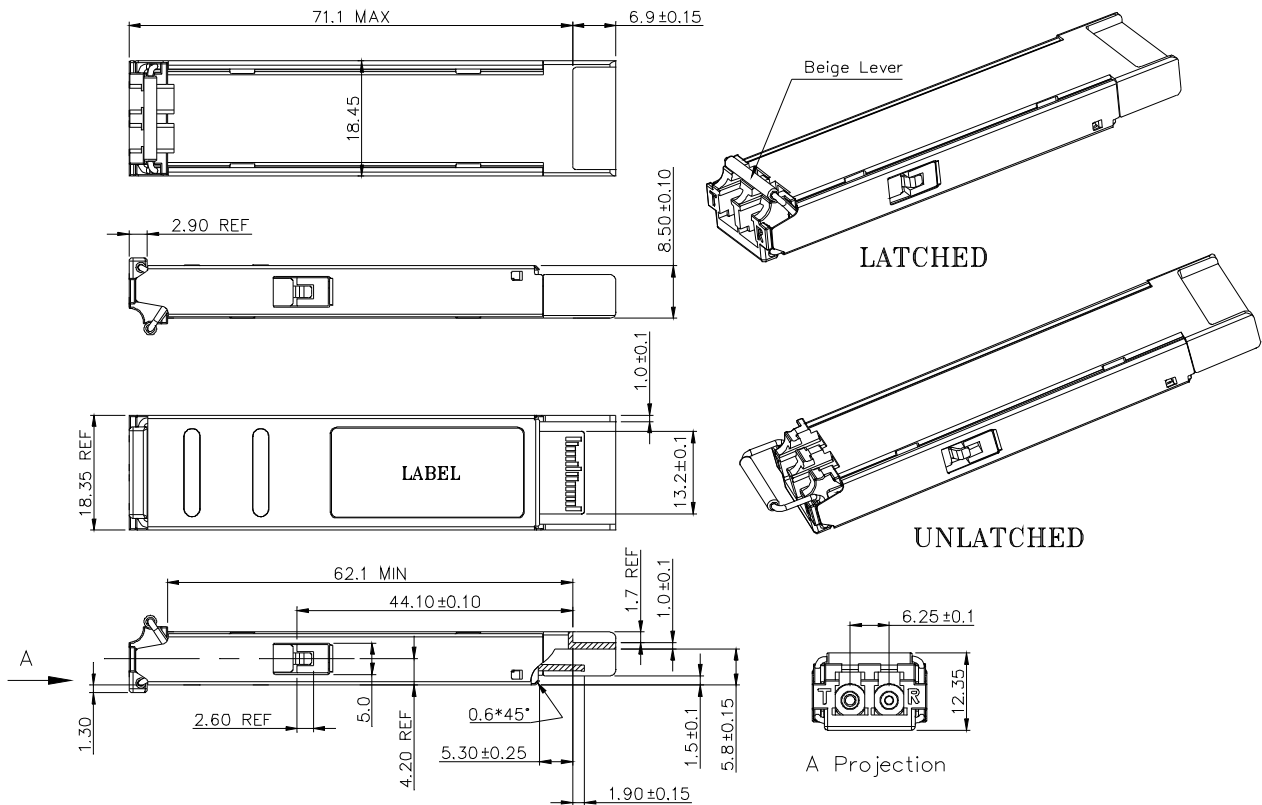
Table 3 PIN Description

PIN	Logic	Signal Name	Description	Note
1		GND	Module Ground	1
2		VEE5	-5.2V Power Supply (Not required)	3
3	LVTTL-I	Mod_Desel	Module De-select; When held low allows module to respond to 2-wire serial interface	
4	LVTTL-O	Interrupt	Interrupt; Indicates presence of an important condition which can be read over the 2-wire serial interface	2
5	LVTTL-I	TX_DIS	Transmitter Disable; Turns off transmitter laser output	
6		VCC5	+5V Power Supply (Not required)	3
7		GND	Module Ground	1
8		VCC3	+3.3V Power Supply	
9		VCC3	+3.3V Power Supply	
10	LVTTL-I/O	SCL	Serial 2-wire interface clock	2
11	LVTTL-I/O	SDA	Serial 2-wire interface data line	2
12	LVTTL-O	Mod_Abs	Indicates Module is not present. Grounded in the Module	2
13	LVTTL-O	Mod_NR	Module Not Ready; Indicating Module Operational Fault	2
14	LVTTL-O	RX_LOS	Receiver Loss Of Signal Indicator	2
15		GND	Module Ground	1
16		GND	Module Ground	1
17	CML-O	RD-	Receiver Inverted Data Output	
18	CML-O	RD+	Receiver Non-Inverted Data Output	
19		GND	Module Ground	1
20		VCC2	+1.8V Power Supply (Not required)	3

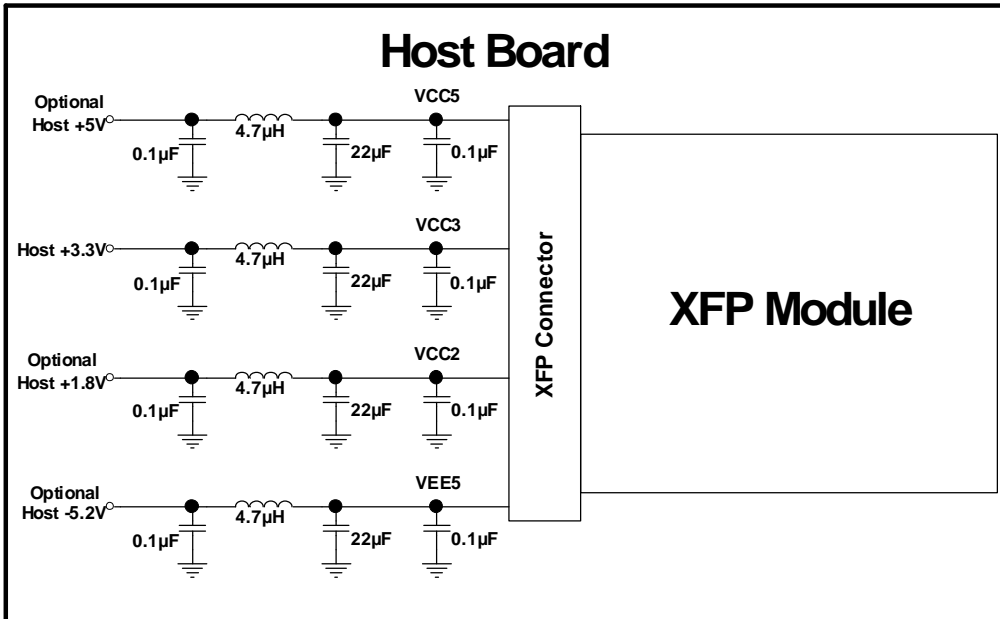
21	LVTTL-I	P_Down/RST	Power down; When high, requires the module to limit power consumption to 1.5W or below. 2-Wire serial interface must be functional in the low power mode. Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle.	
22		VCC2	+1.8V Power Supply (Not required)	3
23		GND	Module Ground	1
24	PECL-I	RefCLK+	Reference Clock Non-Inverted Input, AC coupled on the host board. (Not used. Internally terminated to 50 ohm (100 ohm diff.))	4
25	PECL-I	RefCLK-	Reference Clock Inverted Input, AC coupled on the host board. (Not used. Internally terminated to 50 ohm (100 ohm diff.))	4
26		GND	Module Ground	1
27		GND	Module Ground	1
28	CML-I	TD-	Transmitter Inverted Data Input	
29	CML-I	TD+	Transmitter Non-Inverted Data Input	
30		GND	Module Ground	1

1. Module ground pins GND are isolated from the module case and chassis ground within the module.
2. Shall be pulled up with 4.7K-10Kohms to a voltage between 3.15V and 3.45V on the host board.
3. These PINs are open within module.
4. A Reference Clock input is not required. If present, it will be ignored.

MECHANICAL SPECIFICATION (UNITS IN MM)



RECOMMENDED POWER CIRCUIT SCHEMATIC



RECOMMENDED INTERFACE CIRCUIT

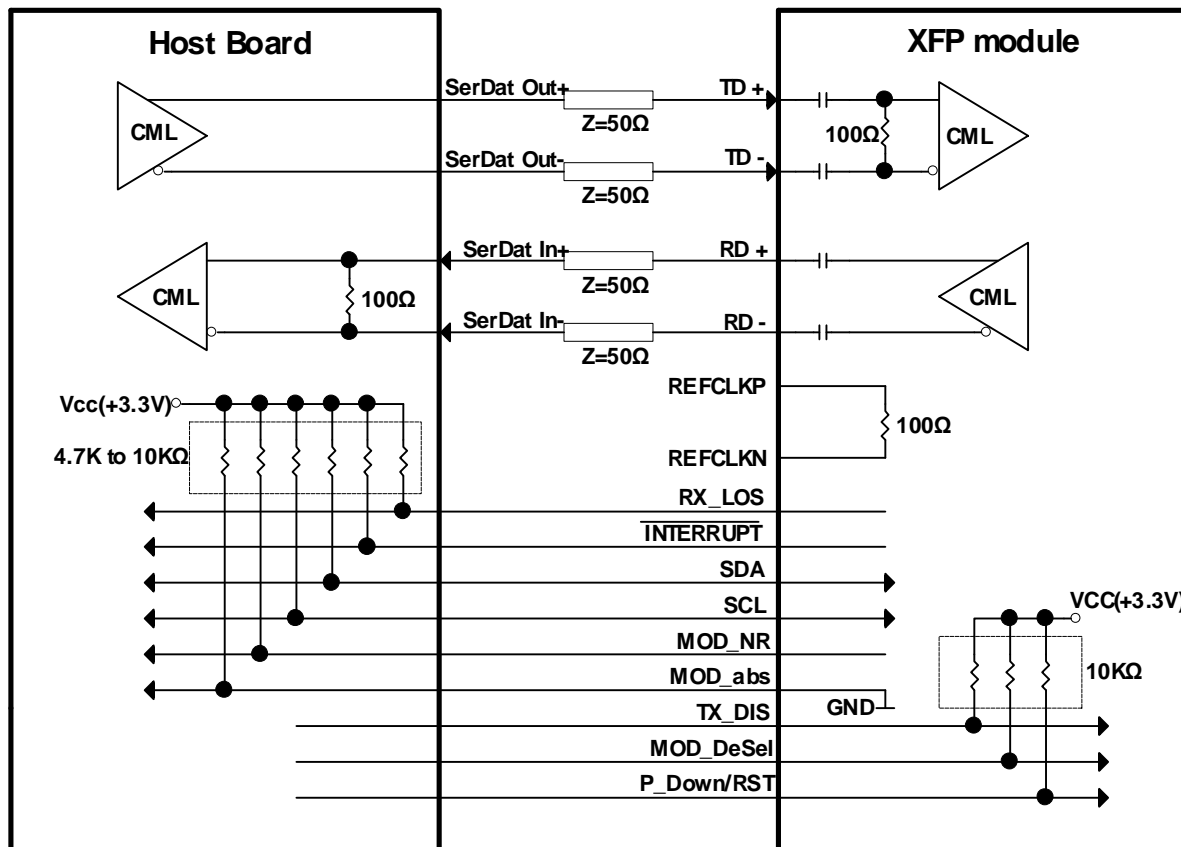


Table 2 Serial ID Memory Contents (Table 01h)

Address	Field Size (Byte)	Name of Filed	Description	Hex
128	1	Identifier	XFP	06
129	1	Ext. Identifier	power consumption <1.5W, no Ref Colck required	10
130	1	Connector type	LC connector	07
131~138	8	Transceiver	10GBASE-SR/SW, 1200-MX-SN-I	88 80 00 00 00 00 00 00
139	1	Encoding	64B/66B, NRZ	90
140	1	BR-Min	9.9Gbps	63
141	1	BR-Max	10.5Gbps	69
142	1	length (SMF)-Km	0	00
143	1	Length (E-50µm)	300m	96
144	1	Length (50 µm)	82m	52
145	1	Length (62.5 µm)	33m	21
146	1	Length (Copper)	0 m	00
147	1	Device Tech	850 nm VCSEL, PIN detector	00
148~163	16	Vendor name	OPTOWAY	4F 50 54 4F 57 41 59 20 20 20 20 20 20 20 20 20
164	1	CDR Support	CDR supports 9.953G ~ 10.52G	E0
165~167	3	Vendor OUI		00 0E FA
168~183	16	Vendor PN	XPM-2100WG	58 50 4D 2D 32 31 30 30 57 47 20 20 20 20 20 20
			XPM-2100BWG	58 50 4D 2D 32 31 30 30 42 57 47 20 20 20 20 20
			XPM-2100AWG	58 50 4D 2D 32 31 30 30 41 57 47 20 20 20 20 20
184~185	2	Vendor rev	ASCII ("31 61" means 1a revision)	xx xx
186~187	2	Wavelength	850 nm	42 68
188~189	2	Wavelength Tolerance	+/- 10nm	07 D0
190	1	Max Case Temp	70deg (for XPM-2100WG)	46
			85deg (for XPM-2100BWG)	55
			85deg (for XPM-2100AWG)	55
191	1	CC_BASE	Check sum of Byte 128 -- 190	
192~195	4	Power Supply	1.2Wmax, 1.2W pd_max , 400mA 3.3V	3C 78 04 00
196~211	16	Vendor SN	ASCII	xx xx xx xx xx xx xx xx xx xx xx xx xx xx xx xx
212~219	8	Date code	ASCII Year (2 Byte), Month (2 Byte), Day (2 Byte)	xx xx xx xx xx xx 20 20
220	1	Diagnostic Monitoring Type	No BER Support, Average Power	08
221	1	Enhanced Options	Optional Soft TX_DISABLE implemented,	
222	1	Aux Monitoring	Optional Soft P_down implemented	60
223	1	CC_EXT	AUX1 for Vcc3.	70
224	1	CC_EXT	Check sum of Byte 192 -- 222	
224~255	32	Vendor Specific		Reserved

Note: Specifications subject to change without notice.

REVISION HISTORY

Version	Subject	Release Date
1.0	Initial datasheet	2007/4/1
2.0	Add XPM-2100BWG for -10 to 85°C	2009/1/1
3.0	Add XPM-2110AWG for -40 to 85°C	2010/7/1
